

ABSTRACT OF THE DISCLOSURE

There is disclosed a semiconductor bonding apparatus which mounts a semiconductor chip via an elastic member disposed between the semiconductor chip and a mounting substrate, comprising a holding section which holds the semiconductor chip facing the mounting substrate, a translatory gas bearing which is connected to the holding section and which is capable of moving the semiconductor chip in a bonding direction with respect to the mounting substrate, a voice coil motor connected to the translatory gas bearing, a load cell which detects a pressing force to be applied to the elastic member by the holding section, and a driving section which generates a driving signal in accordance with the pressing force detected by the load cell to drive the voice coil motor.